

TITLE: VIA PLACEMENT FOR LAYER TRANSITIONS IN FLEXIBLE CIRCUITS WITH HIGH  
DENSITY BALL GRID ARRAYS  
INVENTOR(S): Steven Rosenau, Ershad Ali, Jonathan Simon, Brian Lemoff, Lisa Ann Windover  
Attorney Docket #: AGLT-10021114-1

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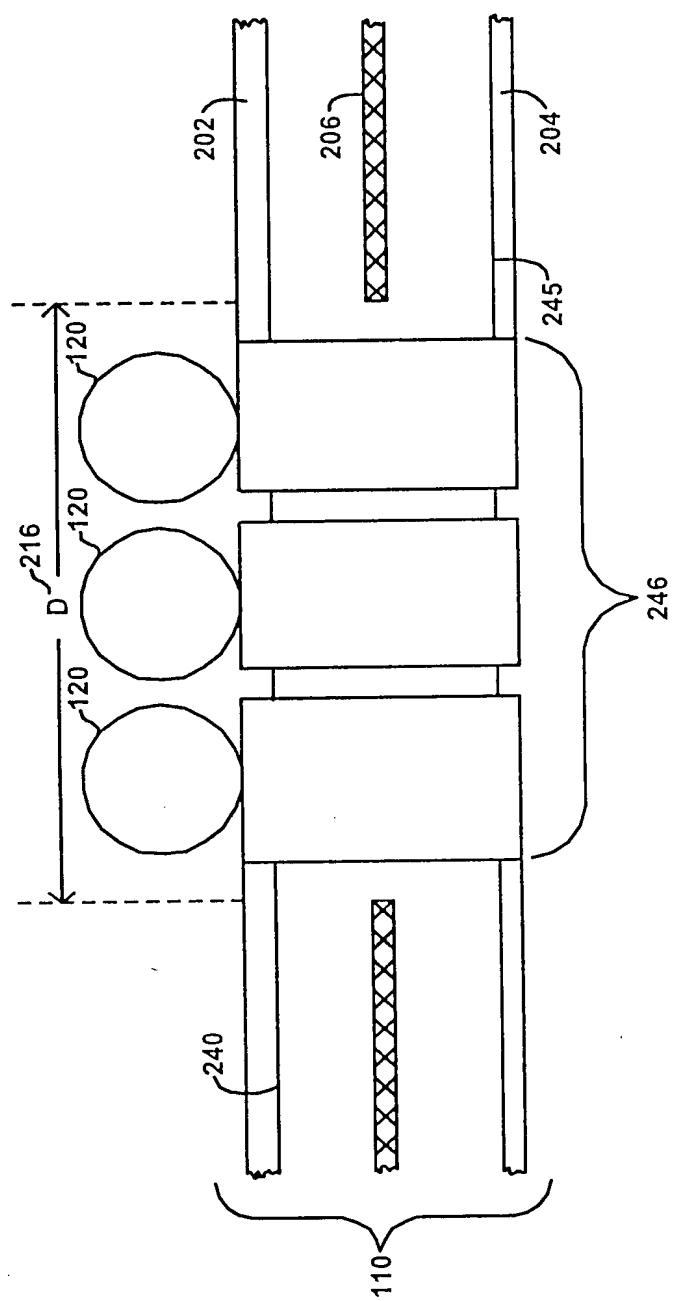
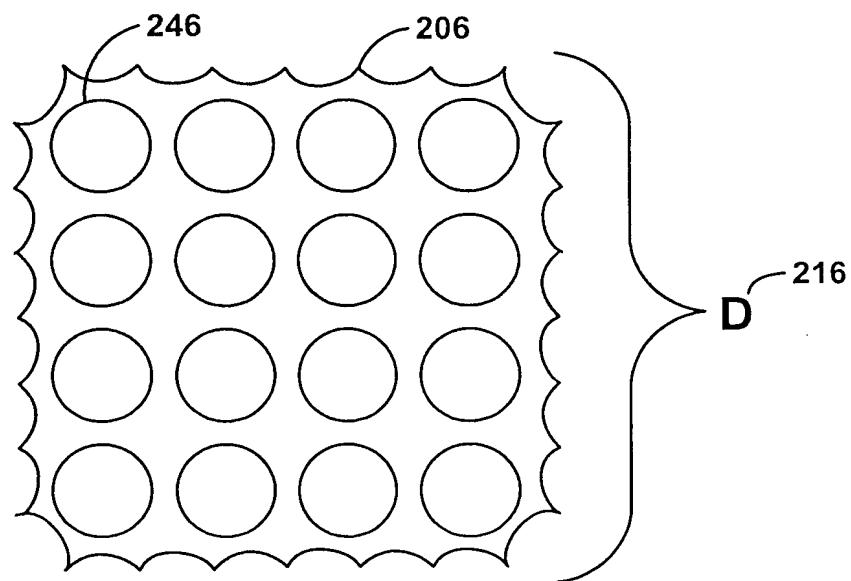


FIG. 1A (Prior Art)

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**FIG. 1B (Prior Art)**

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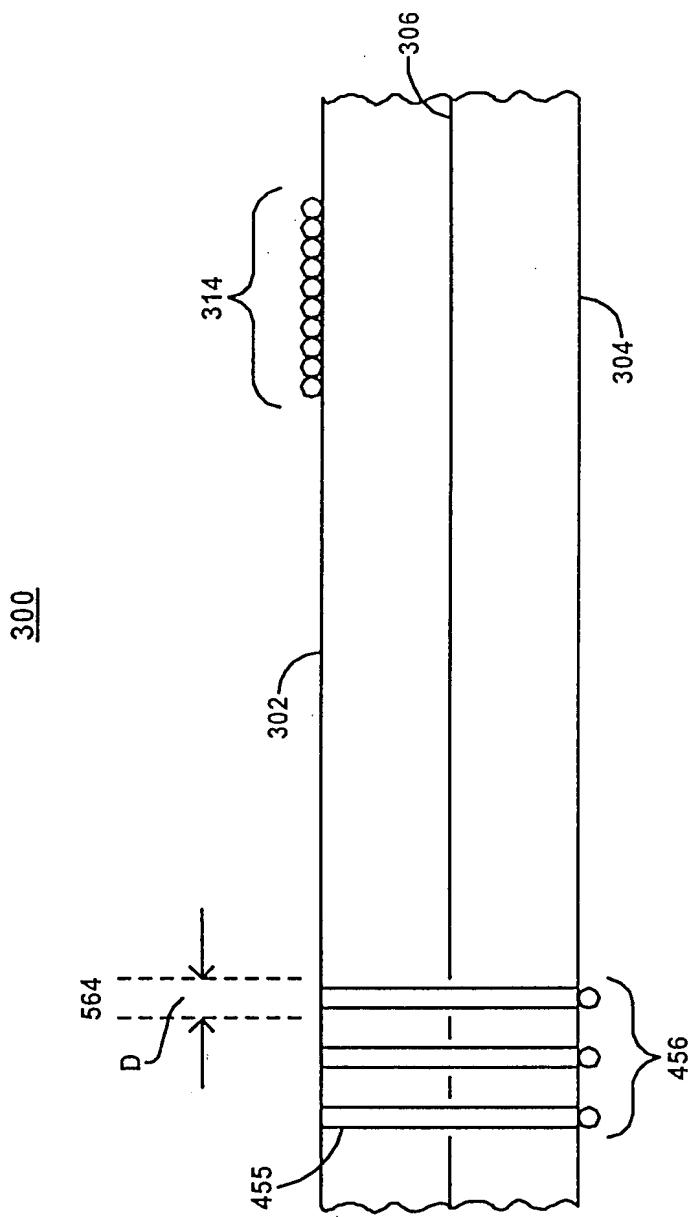


FIG. 2

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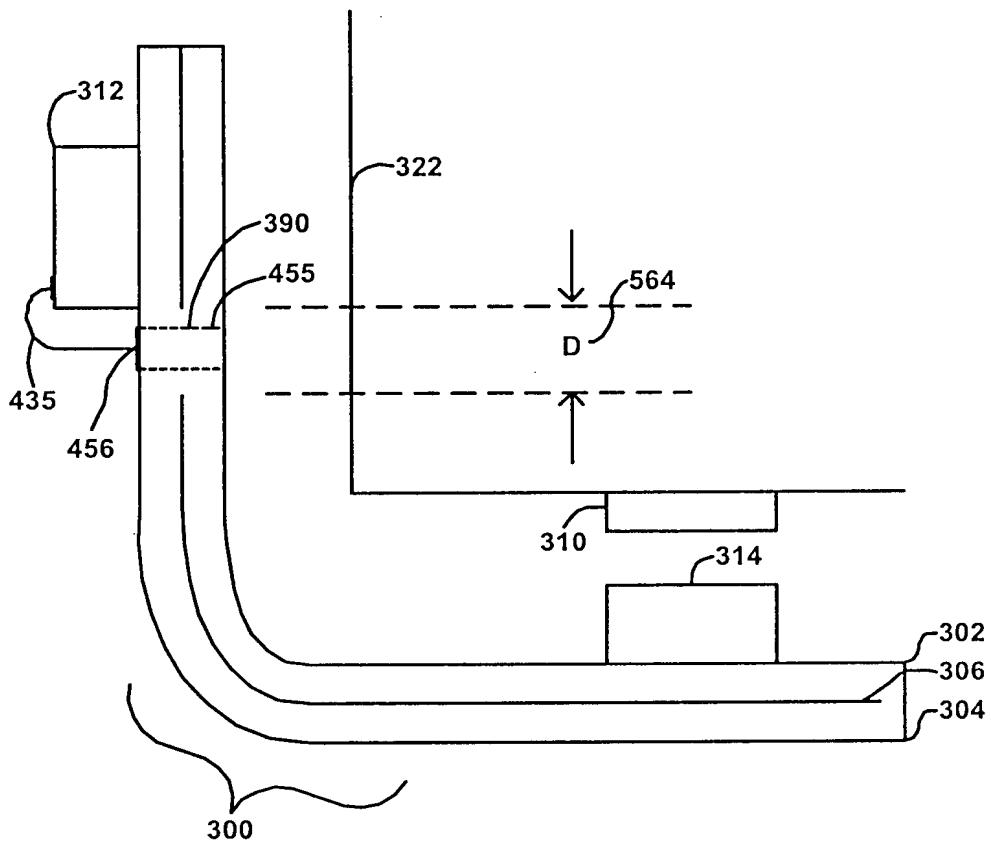


FIG. 3

TITLE: VIA PLACEMENT FOR LAYER TRANSITIONS IN FLEXIBLE CIRCUITS WITH HIGH DENSITY BALL GRID ARRAYS

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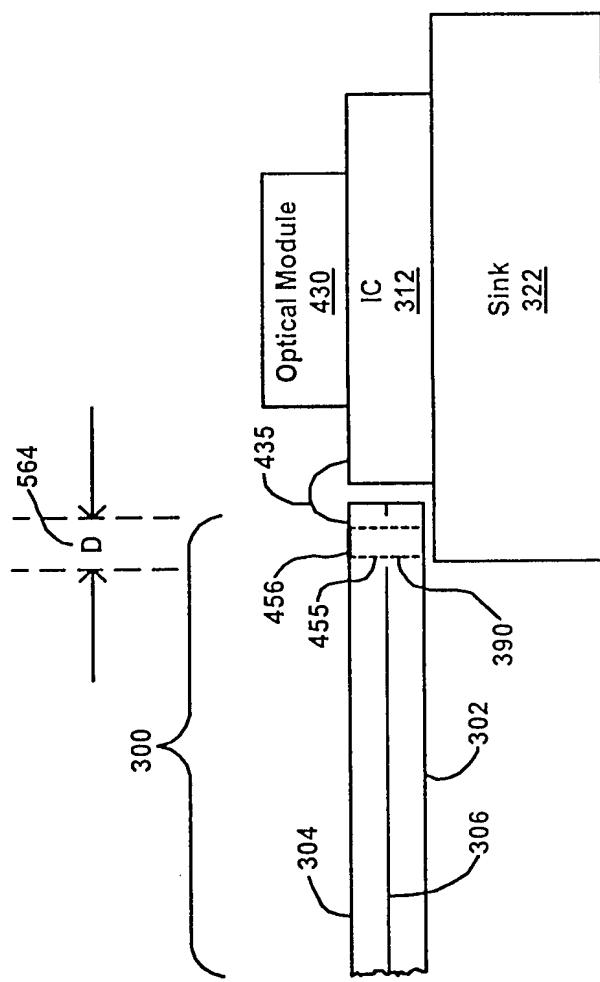
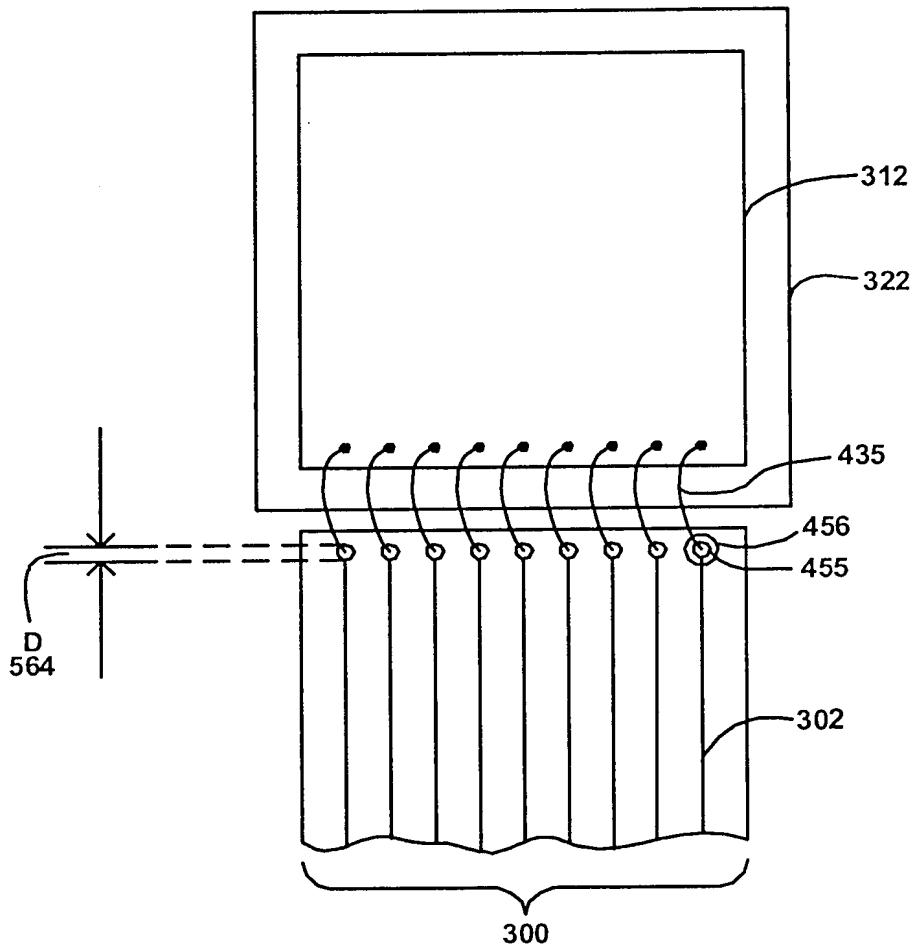


FIG. 4A

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**FIG. 4B**

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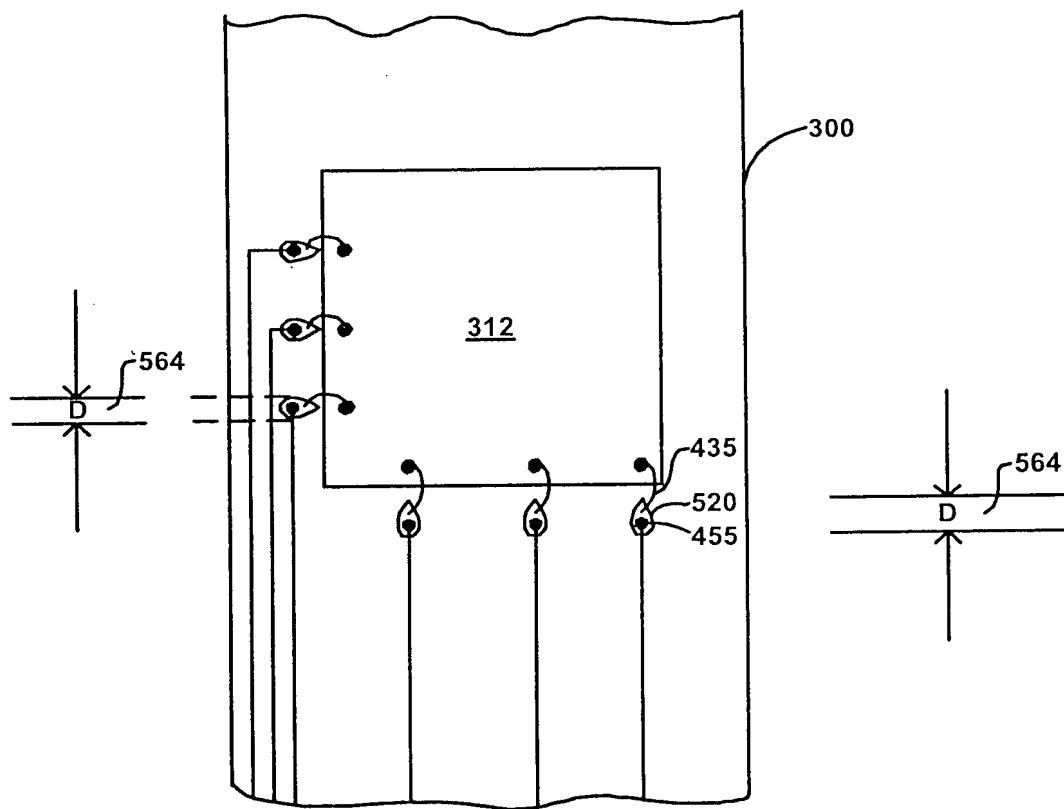


FIG. 5A

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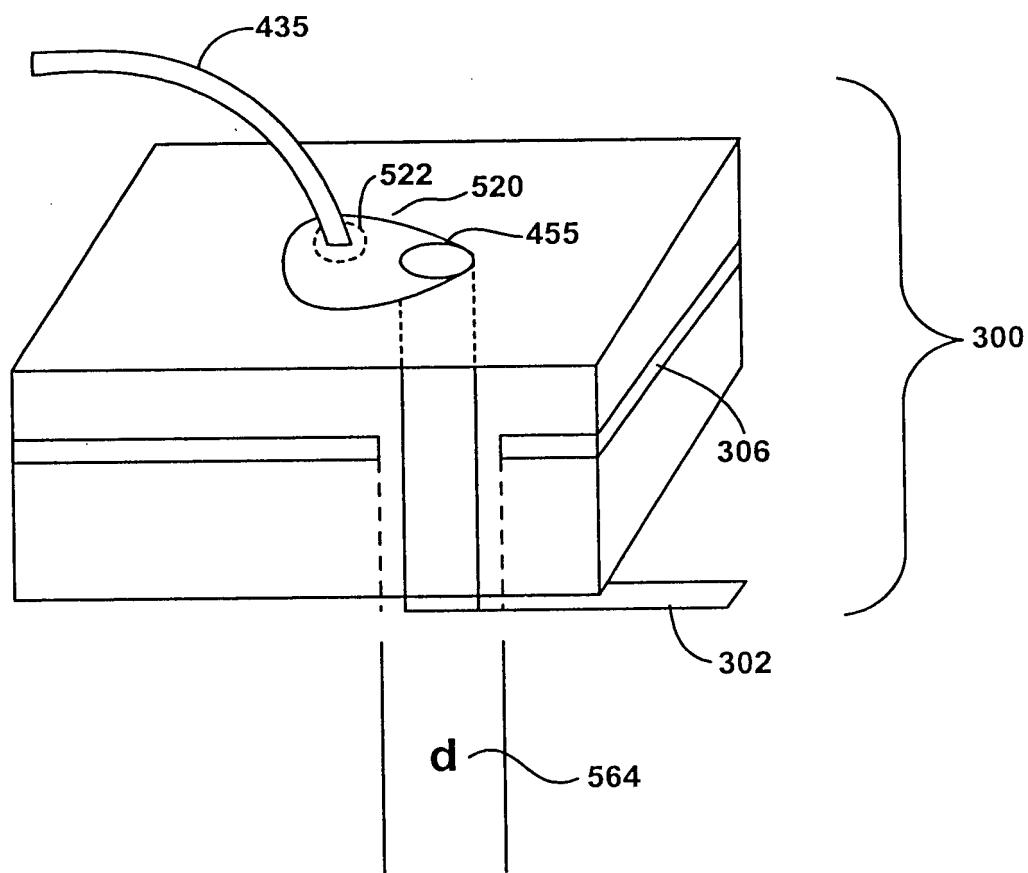


FIG. 5B

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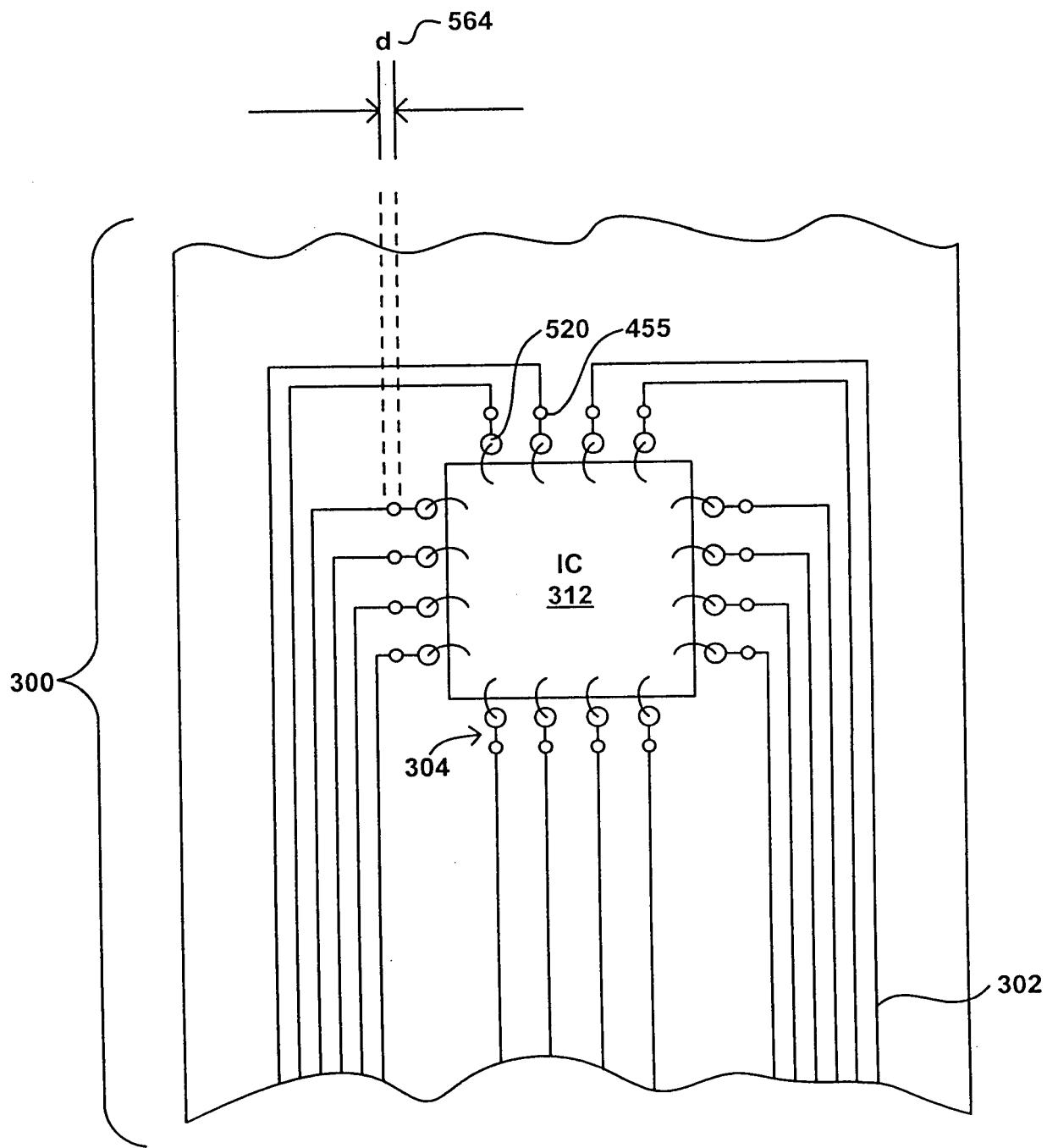


FIG. 5C